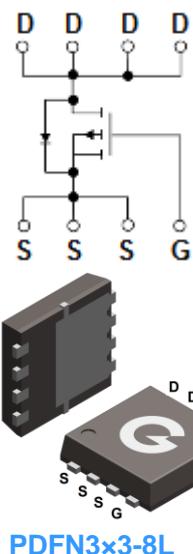


## Features

- Super low gate charge
- 100% E<sub>AS</sub> guaranteed
- Excellent C<sub>dv/dt</sub> effect decline
- Advanced high cell density Trench technology
- Halogen free
- Qualified to AEC-Q101 standards for high reliability

**HF**


## Mechanical Data

- Case: PDFN3x3-8L
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TBL250P06-3DL8	PDFN3x3-8L	5000 pcs / Tape & Reel	250P06

## Maximum Ratings (@ T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	-60	V
Gate-to-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current (T <sub>A</sub> = 25°C) <sup>*1</sup>	I <sub>D</sub>	-7.7	A
Continuous Drain Current (T <sub>A</sub> = 70°C) <sup>*1</sup>		-6.2	A
Pulsed Drain Current <sup>*2</sup>	I <sub>DM</sub>	-55	A
Avalanche Energy, Single Pulsed <sup>*3</sup>	E <sub>AS</sub>	62.9	mJ

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation (T <sub>A</sub> = 25°C) <sup>*4</sup>	P <sub>D</sub>	1	W
Thermal Resistance Junction-to-Air <sup>*4</sup>	R <sub>θJA</sub>	125	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 ~ +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +150	°C

**Electrical Characteristics** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$ , $I_D = -250\mu\text{A}$	-60	-	-	V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = -48\text{V}$ , $V_{GS} = 0\text{V}$ , $T_C = 25^\circ\text{C}$	-	-	-1	$\mu\text{A}$
		$V_{DS} = -48\text{V}$ , $V_{GS} = 0\text{V}$ , $T_C = 55^\circ\text{C}$	-	-	-5	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Static Drain-Source On-resistance <sup>5</sup>	$V_{GS} = -10\text{V}$ , $I_D = -18\text{A}$	-	-	25	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$ , $I_D = -12\text{A}$	-	-	33	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	-1	-	-2.5	V
<b>Dynamic Characteristics</b>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = -15\text{V}$ $f = 1.0\text{MHz}$	-	3635	-	pF
$C_{OSS}$	Output Capacitance		-	224	-	
$C_{RSS}$	Reverse Transfer Capacitance		-	141	-	
<b>Switching Characteristics</b>						
$t_{d(\text{ON})}$	Turn-on Delay Time	$V_{GS} = -10\text{V}$ $V_{DD} = -15\text{V}$ $I_D = -1\text{A}$ $R_G = 3.3\Omega$	-	38	-	ns
$t_r$	Turn-on Rise Time		-	23.6	-	
$t_{d(\text{OFF})}$	Turn-Off Delay Time		-	100	-	
$t_f$	Turn-Off Fall Time		-	6.8	-	
$Q_G$	Total Gate-Charge	$V_{GS} = -4.5\text{V}$ $V_{DD} = -12\text{V}$ $I_D = -12\text{A}$	-	25	-	nC
$Q_{GS}$	Gate to Source Charge		-	6.7	-	
$Q_{GD}$	Gate to Drain (Miller) Charge		-	5.5	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_{SD} = -1\text{A}$ , $V_{GS} = 0\text{V}$	-	-	-1.2	V

Notes:

1. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate
2.  $10\mu\text{s}$  pulse, duty cycle = 1%
3. The  $E_{AS}$  data shows Max. rating. The test condition is  $V_{DD} = -30\text{V}$ ,  $V_{GS} = -10\text{V}$ ,  $L = 0.1\text{mH}$
4. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided
5. Pulse width  $\leq 380\mu\text{s}$ ; duty cycle  $\leq 2\%$

### Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

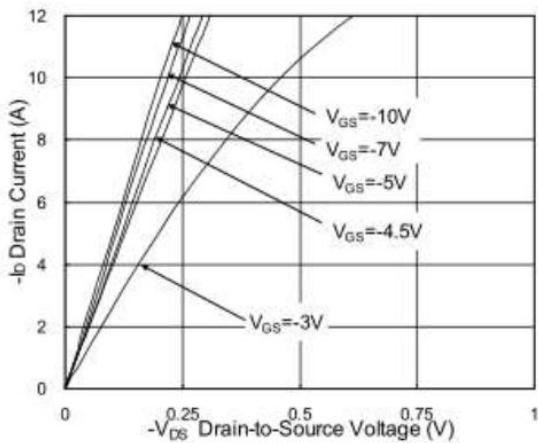


Fig.1 Typical Output Characteristics

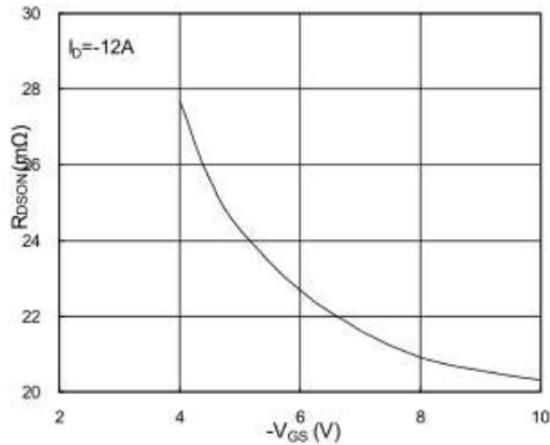


Fig.2 On-Resistance vs. G-S Voltage

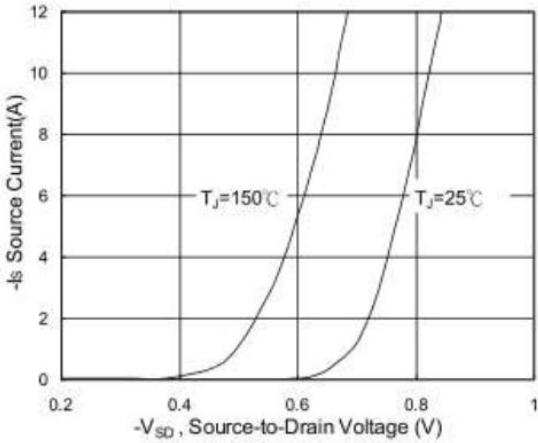


Fig.3 Forward Characteristics of Reverse

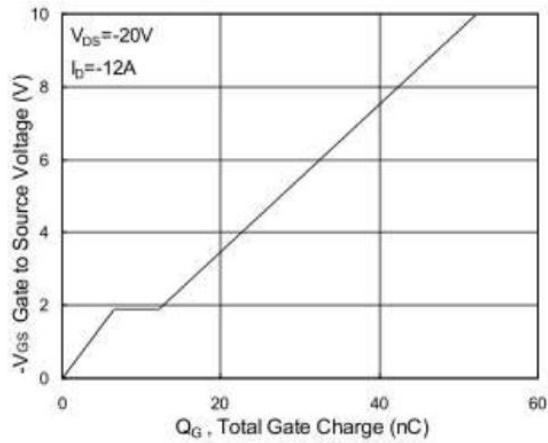


Fig.4 Gate-Charge Characteristics

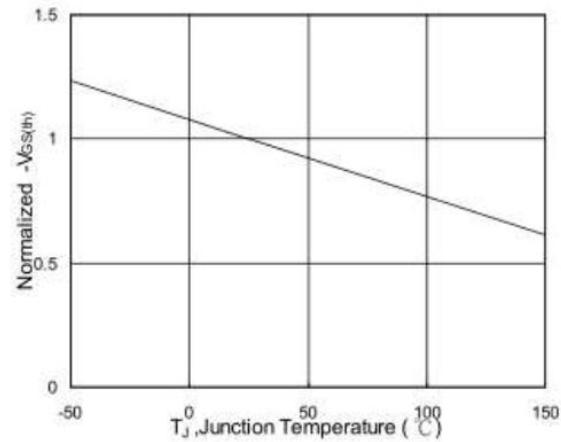


Fig.5 Normalized  $-V_{GS(th)}$  vs.  $T_J$

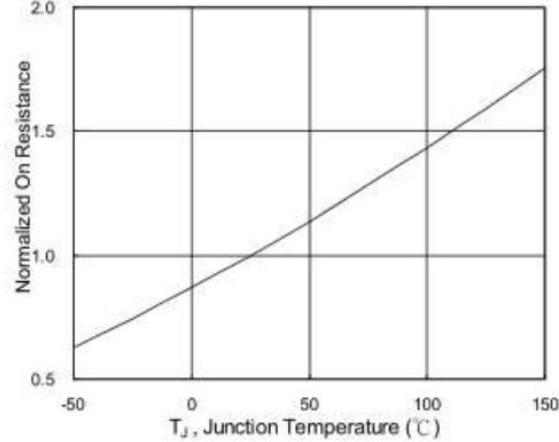
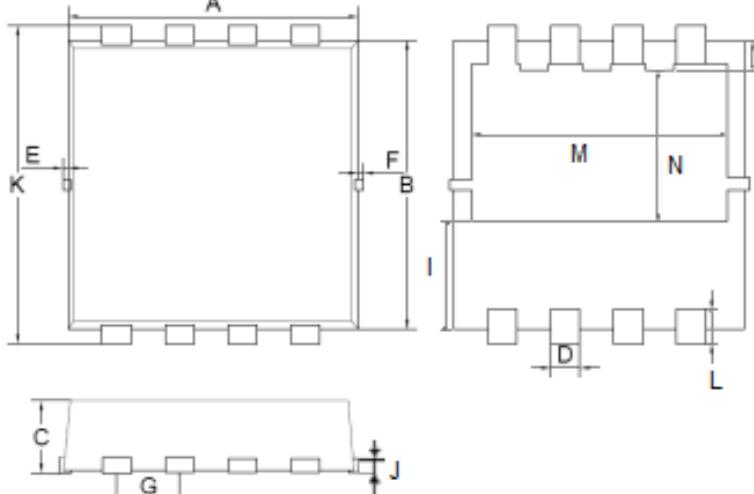
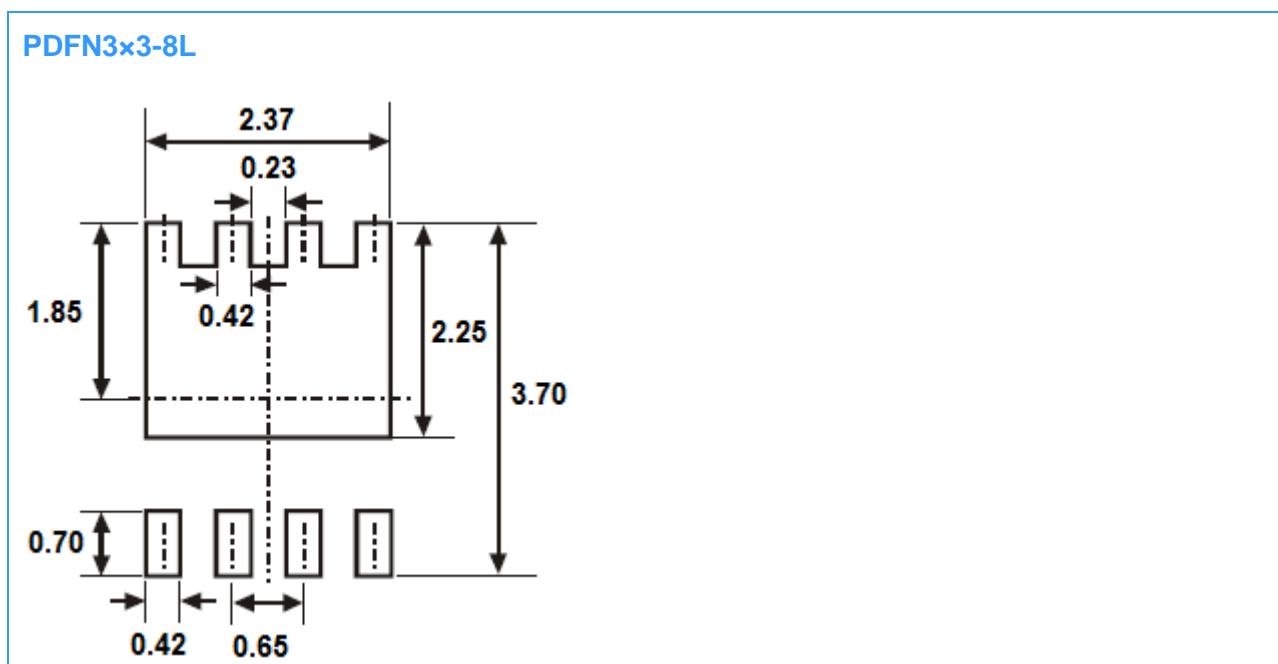


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

**Package Outline Dimensions** (Unit: mm)



PDFN3x3-8L		
Dimension	Min.	Max.
A	2.90	3.10
B	2.90	3.10
C	0.65	0.85
D	0.20	0.40
E	0.00	0.10
F	0.00	0.10
G	0.55	0.75
H	0.20	0.40
I	0.70	1.10
J	0.10	0.20
K	3.15	3.45
L	0.20	0.40
M	2.35	2.55
N	1.500	1.900

**Mounting Pad Layout** (Unit: mm)

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